



LEXCMGX

Laminate

R-1515A

Prepreg

R-1410A

Low CTE IC substrate materials

Achieve more functionality (multi-pin and integrated circuit) the large-sized Package by excellent modulus and highly heat resistant property.

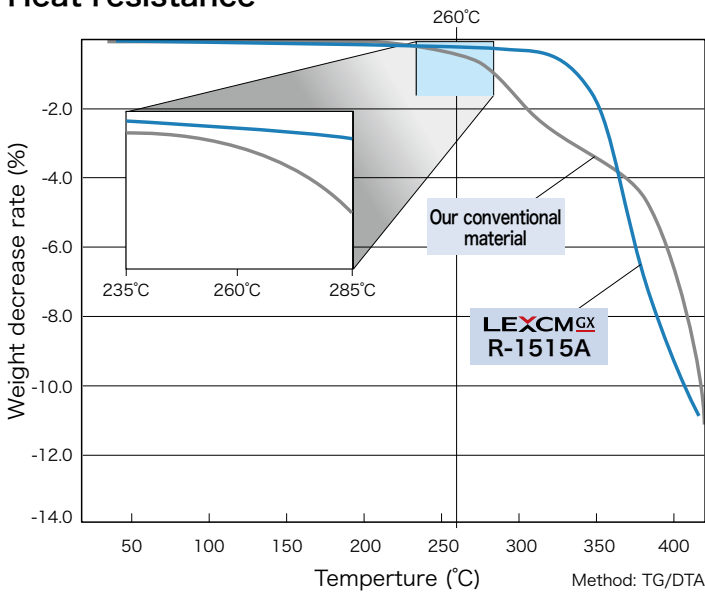
Flexural modulus
25°C 27GPa

CTE x, y-axis
11-13ppm/°C

Tg(DMA) 205°C

Applications
IC Package
IC substrate

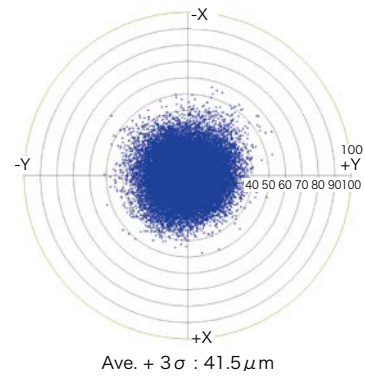
Heat resistance



Weight decrease @260°C

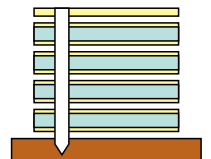
LEXCMGX R-1515A	0.2%
Our conventional material	0.5%

Positioning accuracy



Condition

Drill size	0.15mm φ
Flute length (ℓ)	3.0mm
Spindle speed	200krpm
Chip load	10 μm/rev
Hit count	20,000
Entry board	LE 800
Board thickness	0.4mm
Copper foil thickness	12/12 μm
Stack count	4



General properties

Item	Test method	Condition	Unit	LEXCMGX R-1515A
Glass transition temp.(Tg)	DMA*2	A	°C	205
Thermal decomposition temp.(Td)	TGA	A	°C	390
CTE x-axis	14GHz Internal method	A	ppm/°C	11-13
CTE y-axis				11-13
Flexural modulus*1	JIS C 6481	25°C	GPa	27
		250°C		10

The sample thickness is 0.1 mm.

*1 0.8mm *2 Measurement in bending mode

Please see our website for Notes before you use.

Our Halogen-free materials are based on JPCA-ES-01-2003 standard and others.

The above data are typical values and not guaranteed values.

industrial.panasonic.com/ww/electronic-materials

Panasonic Industry R-1515A

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